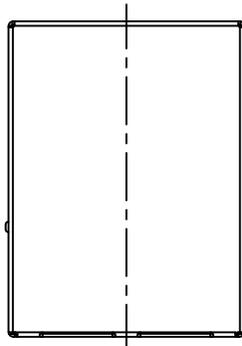
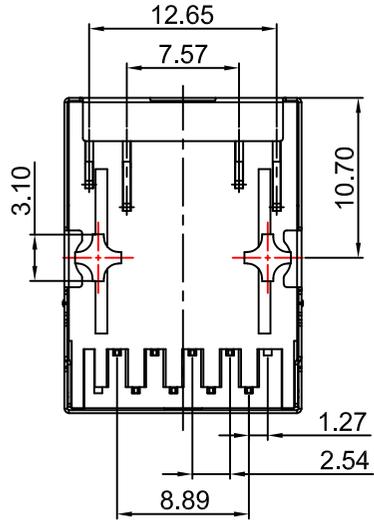
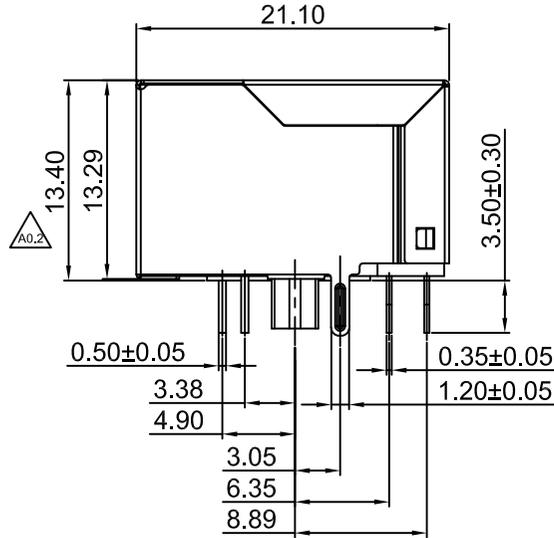
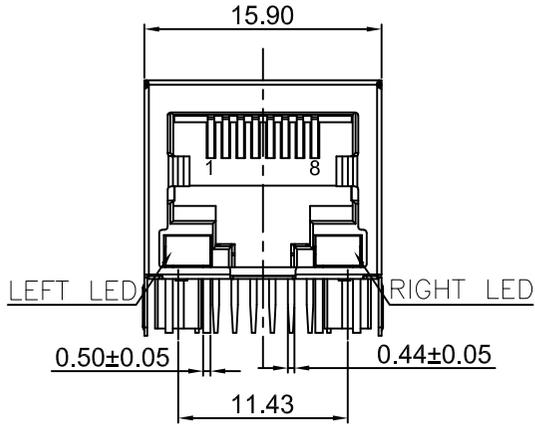


# GP Component

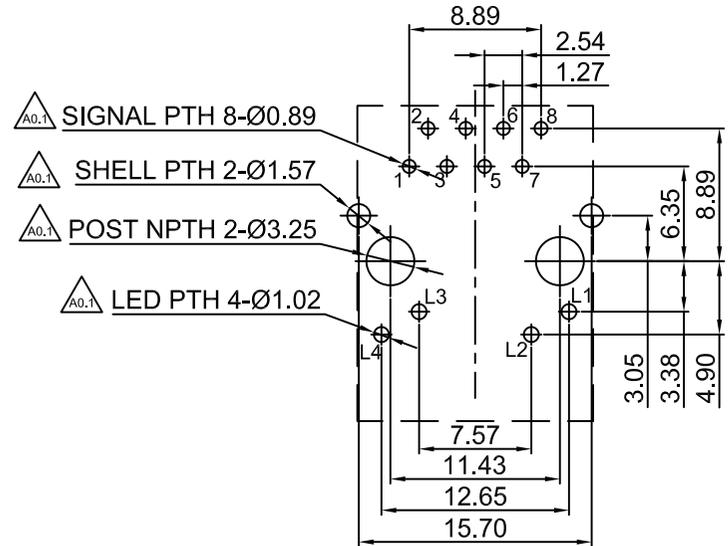
## 1. MECHANICAL DIMENSIONS :



Printing:

MATRIX  
MRJF-11T1740THF  
YYWW

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2022/12/06	Vince
A0.1			Add Pcb Layout label	2023/12/25	Vince
A0.2			Modify Size	2024/01/04	Vince



Suggested PCB Layout(Top View)  
(Tolerance:±0.05)

### 1.Material:

- 1.1 Housing: LCP UL94V-0 Black.
- 1.2 Insert core:LCP UL94V-0 Black.
- 1.3 Contact :Phosphor Bronze,Gold plated on contact area 6u",Tin plated on solder area 80u" min, overall nickel plating 30u" min.
- 1.4 Input Terminal : Brass,Tin plated on solder area 80u" min, Ni underplated overall 30u" min.
- 1.5 Metal shielding:Copper alloy with Nickel plated.

### 2.Environmental requirements:

- 2.1 Lead-free process,compliant RoHS,halogen-free.



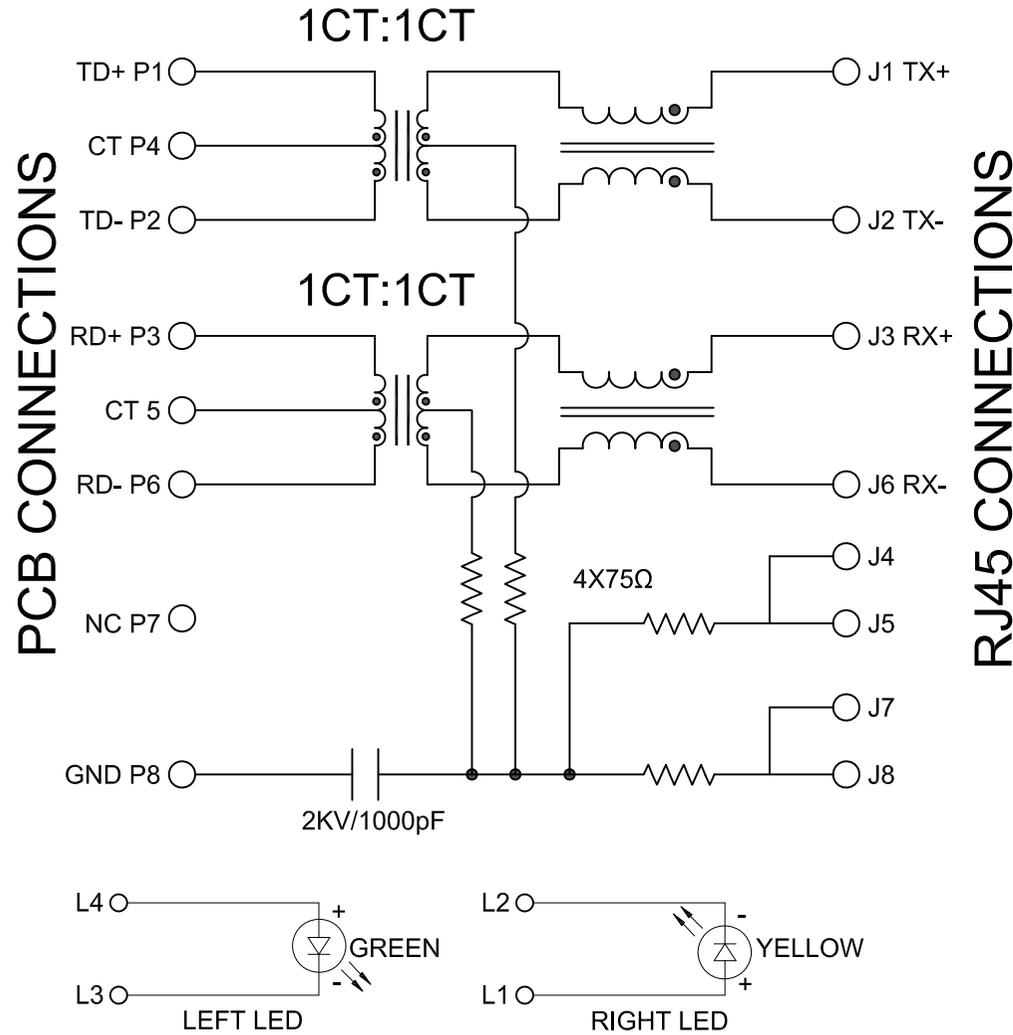
Matrix Electronics Co., Ltd

<b>TOLERANCE:</b> X X.X ±0.38 X.XX ±0.25 X.XXX ±0.13 ANGLE: ±3°	<b>DESIGN BY :</b> Vince Chen	<b>DATE :</b> 2024/01/04	<b>PART NAME:</b> RJ45 CONN,W/LED,SP,SC 100/10MBPS,FILTER	
	<b>CHECKED BY:</b> Hanson Huang	<b>DATE :</b> 2024/01/04	<b>PART NO.</b>	MRJF-11T1740THF
 <b>UNIT: mm [inch]</b> <b>SCALE:1:1 SIZE:A4</b>	<b>APPROVED BY1:</b> Richard Hsieh	<b>DATE :</b> 2024/01/04	<b>MOLD NO.</b>	NA
	<b>APPROVED BY2:</b> Richard Hsieh	<b>DATE :</b> 2024/01/04	<b>DRAW NO.</b>	
			<b>SHEET NO.</b>	1 OF 3

# GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2022/12/06	Vince
A0.1			Add Pcb Layout label	2023/12/25	Vince
A0.2			Modify Size	2024/01/04	Vince

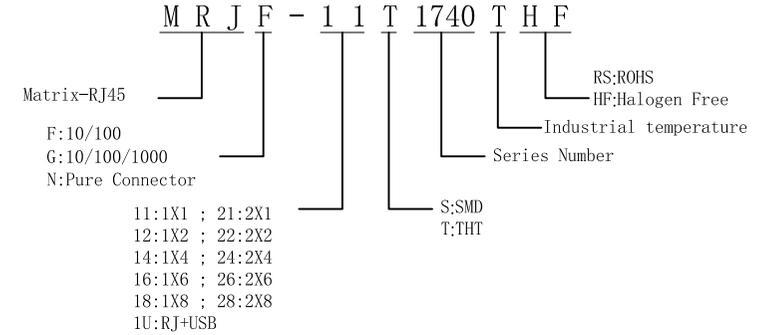
## 2. SCHEMATIC:



## 3. Electrical Specification @25°C:

- 3.1 Inductance: 350uH Min With 8mA DC bias.
- 3.2 Hi-Pot Test: Input to Output 2250VDC/1mA.
- 3.3 Insertion loss : 1-100MHZ -1dB max.
- 3.4 Return loss : 1-30MHZ -18dB min.  
30-60MHZ -16dB min.  
60-80MHZ -12dB min.  
80-100MHZ -10dB min.
- 3.5 Common Mode Rejection:1-100MHZ -30dB min.
- 3.6 Cross Talk:1-100MHZ -30dB min.
- 4. Operating and Storage Temperature:
- 4.1 Operating Temperature : -40°C to +85°C.
- 4.2 Storage Temperature : -40°C to +85°C.
- 5. Wave soldering peak temperature:260°C.

MATRIX PART NO :

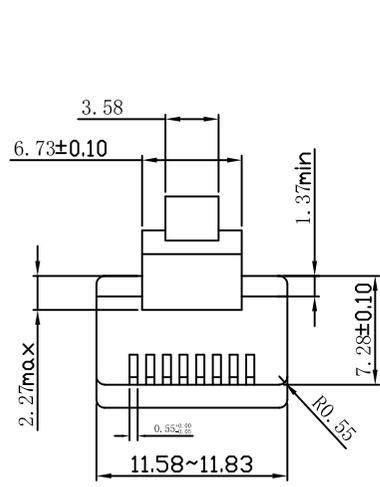


Emitting Color	$\lambda$ p(nm)	Vf@If=20mA
GREEN	565	1.8-2.5V
YELLOW	585	1.8-2.5V

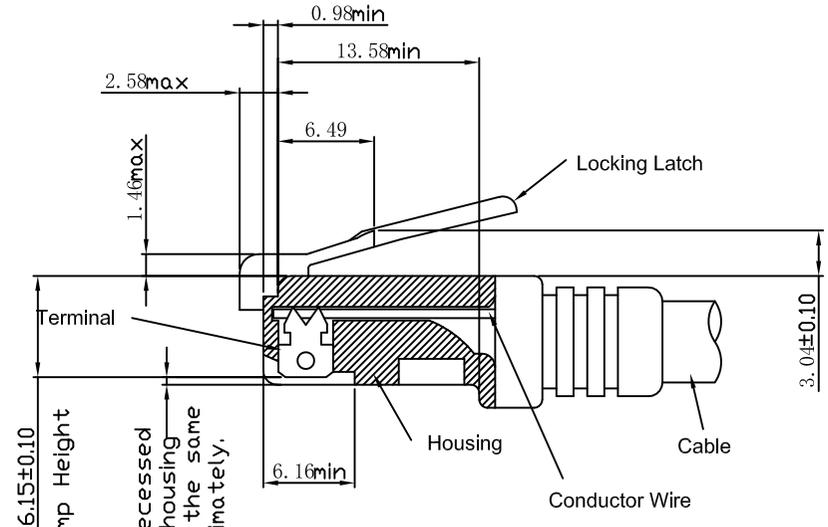
Matrix Electronics Co., Ltd				
TOLERANCE: X X.X X.XX X.XXX ANGLE: ±3°	DESIGN BY : Vince Chen	DATE : 2024/01/04	PART NAME: RJ45 CONN, W/LED, SP, SC 100/10MBPS, FILTER	
 UNIT: mm [inch] SCALE:1:1 SIZE:A4	CHECKED BY: Hanson Huang	DATE : 2024/01/04	PART NO.	MRJF-11T1740THF
	APPROVED BY1: Richard Hsieh	DATE : 2024/01/04	MOLD NO.	NA
	APPROVED BY2: Richard Hsieh	DATE : 2024/01/04	DRAW NO.	
			SHEET NO.	2 OF 3

# GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2022/12/06	Vince
A0.1			Add Pcb Layout label	2023/12/25	Vince
A0.2			Modify Size	2024/01/04	Vince



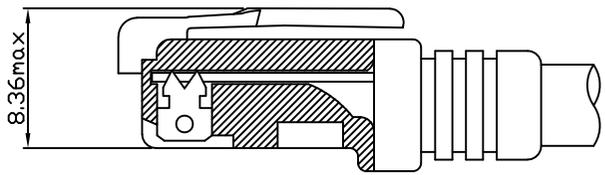
- \* There must be no damage to housing or locking latch. There must be no nicks or cuts in cable.
- \* Durability : 750 cycles generally



All contacts recessed below top of housing and must be at the same height approximately.

FOLLOW SPECIFICATION : FCC, PART 68, SUBPART F FIGURE 68.500 (C)(2)(i) AND IEC 603-7 FIGURE 23 & 24

## STANDARD MODULAR PLUG ASSEMBLY



FOLLOW SPECIFICATION : FCC, PART 68, SUBPART F FIGURE 68.500 (C)(2)(ii)

 <b>Matrix Electronics Co., Ltd</b>			
<b>TOLERANCE:</b> X.X ±0.38 X.XX ±0.25 X.XXX ±0.13 ANGLE: ±3°	<b>DESIGN BY :</b> Vince Chen	<b>DATE :</b> 2024/01/04	<b>PART NAME:</b> RJ45 CONN, W/LED, SP, SC 100/10MBPS, FILTER
	<b>CHECKED BY:</b> Hanson Huang	<b>DATE :</b> 2024/01/04	<b>PART NO.</b> MRJF-11T1740THF
  <b>UNIT: mm [inch]</b> <b>SCALE:1:1 SIZE:A4</b>	<b>APPROVED BY1:</b> Richard Hsieh	<b>DATE :</b> 2024/01/04	<b>MOLD NO.</b> NA
	<b>APPROVED BY2:</b> Richard Hsieh	<b>DATE :</b> 2024/01/04	<b>DRAW NO.</b> (blank)
			<b>SHEET NO.</b> 3 OF 3